

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In Re Application of:

Takagi

Serial No.: UNASSIGNED (Parent 10/202,698)

Group Art Unit: UNASSIGNED  
(Parent 2812)

Examiner: UNASSIGNED

Filed: Herewith (Parent July 25, 2002)

Docket No. 250604-1011

For: **Heating Furnace and Semiconductor Wafer-Holding Jig Assembly and Process  
of Manufacturing Semiconductor Devices**

**PRELIMINARY AMENDMENT**

Mail Stop – Patent Application  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Before examination of the above-referenced patent application, please enter the following amendments.

In the Specification

Please amend the specification, on page 1, line 3 by inserting the following immediately following the title of the invention:

CROSS-REFERENCE TO RELATED APPLICATIONS

This application is a division of U.S. patent application serial number 10/202,698, filed on July 25, 2002.